

Subst. Form PTO-1449 APPLICANT'S INFORMATION DISCLOSURE STATEMENT	Atty. Docket No.: 2802-257-058	Serial No.: 10/045,924
	Applicant: Michael Bunyan, et al	
	Filing Date: Concurrently Herewith	Group: 1772

U.S. PATENT DOCUMENTS

Initial*		Document No.	Date	Name	Class	Subcl.	Filing Date
TSPE	AA	2,311,526	02/16/43	Ferguson, et al.	—	—	
	AB	3,332,055	07/18/67	Bogner	—	—	
	AC	3,609,104	09/28/71	Ehrreich, et al.	—	—	
	AD	3,928,907	12/30/75	Chisholm	—	—	
	AE	4,299,715	11/10/81	Whitfield, et al.	—	—	
	AF	4,384,610	05/24/83	Cook, et al.	—	—	
	AG	4,389,340	06/21/83	Levy	—	—	
	AH	4,466,483	08/21/84	Whitfield et al.	—	—	
	AI	4,473,113	09/25/84	Whitfield, et al.	—	—	
	AJ	4,487,856	12/11/84	Anderson et al.	—	—	
	AK	4,533,685	08/06/85	Hudgin et al.	—	—	
	AL	4,546,411	10/08/85	Kaufman	—	—	
	AM	4,561,011	12/24/85	Kohara et al.	—	—	
	AN	4,575,432	03/11/86	Lin et al.	—	—	
	AO	4,602,678	07/29/86	Fick	—	—	
	AP	4,654,754	03/31/87	Danzkowski	—	—	
	AQ	4,685,987	08/11/87	Fick	—	—	
	AR	4,722,960	02/02/88	Dunn et al.	—	—	
	AS	4,755,249	07/05/88	DeGree et al.	—	—	
	AT	4,764,845	08/16/88	Artus	—	—	
	AU	4,782,893	11/00/88	Thomas	—	—	
	AV	4,842,911	06/27/89	Fick	—	—	
	AW	4,855,002	08/08/89	Dunn et al.	—	—	
	AX	4,869,954	09/26/89	Squitieri	—	—	
	AY	4,915,167	04/10/90	Altoz	—	—	
	AZ	4,965,699	10/23/90	Jorden et al.	—	—	
	BA	4,974,119	11/27/90	Martin	—	—	
	BB	4,979,074	12/18/90	Morley et al.	—	—	
	BC	5,052,481	10/01/91	Horvath et al.	—	—	
	BD	5,060,114	10/22/91	Peinberg et al.	—	—	
	BE	5,061,549	10/29/91	Shores	—	—	
	BF	5,137,959	08/11/92	Block et al.	—	—	
	BG	5,167,851	12/01/92	Jamison, et al	—	—	
	BH	5,194,480	03/16/93	Block et al.	—	—	
	BI	5,213,868	05/25/93	Liberty et al.	—	—	
	BJ	5,250,209	10/05/93	Jamison, et al	—	—	
	BK	5,298,791	03/29/94	Liberty et al.	—	—	
BPE	BL	5,302,344	04/12/94	Perlman	—	—	

BPE	BM	5,321,682	06/21/94	Zarovi et al.	—	—	
	BN	5,352,731	10/04/94	Nakano et al.	—	—	
	BO	5,372,683	12/13/94	Shores	—	—	
	BP	5,470,027	11/28/95	Call, et al.	—	—	
	BQ	5,533,256	07/09/96	Call, et al.	—	—	
	BR	5,545,473	08/13/96	Ameen, et al.	—	—	
	BS	5,602,221	02/11/97	Bennett et al.	—	—	
	BT	5,679,457	10/21/97	Bergerson	—	—	
	BU	5,770,318	06/23/98	Friedman	—	—	
	BV	5,781,412	07/14/98	de Sargo	—	—	
	BW	5,796,582	08/18/98	Katchmar	—	—	
	BX	5,798,171	08/25/98	Olson	—	—	
	BY	5,930,893	08/03/99	Eaton	—	—	
BPE	BZ	5,944,322	08/31/99	Coff et al.	—	—	

FOREIGN PATENT DOCUMENTS

		Document No.	Date	Country			
BPE	CA	5 - 138396	5-1993	Japan	—	—	
OTHER PRIOR ART							
BPE	CB	Copy of International Application Published Under the Patent Cooperation Treaty No. WO 96/37915					
	CC	Copy of International Application Published Under the Patent Cooperation Treaty No. WO 97/41599					
	CD	Copy of International Application Published Under the Patent Cooperation Treaty No. WO 97/41599					
	CE	Article entitled "Thermally Conductive Adhesives for Electronic Packaging, authored by Carol Latham, President of Thermagon, Inc. dated July 1991.					
	CF	Letter dated July 25, 2000 from Eugene Lieberstein of Anderson Kill & Olick, P.C.					
	CG	Invoices dated May 15, 1992 and July 6, 1993 of Thermagon, Inc.					
	CH	Technical Data Sheet Ablefilm® 5025E, dated March, 1992 of Ablestik, entitled Electrically Conductive Adhesive Film.					
	CI	Technical Data Sheet Ablefilm® 563K, dated November, 1995 of Ablestik, entitled Thermally Conductive Adhesive Film.					
	CJ	Technical Data Sheet Ablefilm® 566K, dated November, 1995 of Ablestik, entitled Low Temperature Cure Adhesive Film.					
	CK	Article entitled T-gon 100 Series, Thermally Conductive Epoxy Adhesive Films, dated June 10, 1997 of Thermagon, Inc.					
	CL	AI Technology Data Sheet for Cool-Pad TP7105, revised February, 1992.					
	CM	AI Technology Data Sheet for Cool-Pad TP7608, revised February, 1992.					
	CN	AI Technology Data Sheet for Cool-Pad TP7208, revised February, 1992.					
	CO	AI Technology Data Sheet for Cool-Pad TP7205, revised February, 1992.					
	CP	AI Technology Data Sheet for Thermoplastic TP7165, revised October, 1994.					
	CQ	AI Technology Data Sheet for Cool-Pad TP7605, revised October, 1994.					
	CR	AI Technology Data Sheet for Cool-Pad TP7609, revised August 12, 2000.					
	CS	Article authored by L.M Leung and K. K. T. Chung entitled Zero-stress Film Adhesive for Substrate Attach, published in Hybrid Circuits NO. 18, January 1989.					
	CT	Letter dated August 17, 2000 from Clement A. Borard of Dann, Dorfman, Herrell & Skillman					
	CU	Thermal Products Group - Grease Replacement Products To Support Pentium and Pentium II Applications 9/16/98					
BPE	CV	IBM Technical Disclosure Bulletin, Vol. 25, No. 11A April 1983 Pliable Heat-Conducting Sheet Material For Semiconductor Packages. R. H. Lacombe and H. Lee					

BPE	CW	IBM Technical Disclosure Bulletin, Vol. 24, No. 12 May 1982 Chip Cooling Employing Alloys Having Different Solidus Temperatures, J. K. Hassan, S. Oktay and J. Peivanaz
	CX	IBM Technical Disclosure Bulletin, Vol. 27, No. 7A December 1984 Cooling Assembly For Solder-Bonded Semiconductor Devices - J. L. Horvath
	CY	IBM Technical Disclosure Bulletin, Vol. 35, No. 7 December 1992 Thermally Conductive, Reworkable, Elastomeric Interposer For Chip-to-Heat Sink Attachment
	CZ	AI Technology Invoice No. 6420 dated February 12, 1993.
	DA	AI Technology Invoice No. 7344 dated August 27, 1993.
	DB	AI Technology Invoice No. 5657 dated September 14, 1992.
	DC	AI Technology Invoice No. 4580 dated March 24, 1993.
	DD	AI Technology Invoice No. 5370 dated July 27, 1992.
	DE	AI Technology Invoice No. 4964 dated May 27, 1992.
	DF	AI Technology Invoice No. 8303 dated March 18, 1994.
	DG	AI Technology Invoice No. 8789 dated July 18, 1994
	DH	ORCUS inc. THERMAPHASE - Thermal Interface Materials for Electronics: Unique Characteristics, Lowest Thermal Resistance
	DI	Technical Bulletin #77 Chomerics - CHO-THERM Thermal Interface Materials 1997
	DJ	Technical Bulletin #78 Chomerics - CHO-THERM Thermal Interface Materials 1998
	DK	Packaging Ideas, Edited by Howard Markstein, Interface Materials Offer Heat Transfer and Isolation
BPE	DL	EARL'S Pressure Master - Engine Gaskets Seals - 1996 Earl's Performance Products

Examiner:

Date Considered:

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if in conformance and not considered. Include copy of this form with next communication to applicant.

360/22971ALA.20G